

Announces Agreement with GeneSiC

Featuring SiC Schottky Diodes in Bare Die Form

GeneSiC is a pioneer and world leader in Silicon Carbide technology, while also invested in high power Silicon technologies. The global leading manufacturers of industrial and defence systems depend on GeneSiC's technology to elevate the performance and efficiency of their products. GeneSiC hold leading patents on wide band gap power device technologies

Combining our bare die expertise with GeneSiC technology provides the module designer with a leading edge power product and world class technical support.

Whether you want to use SiC schottky bare die to improve your existing application or to gain a performance edge in your next generation application, trust Microcross Components.

For additional technical information and worldwide sales support, please contact your nearest global representative:

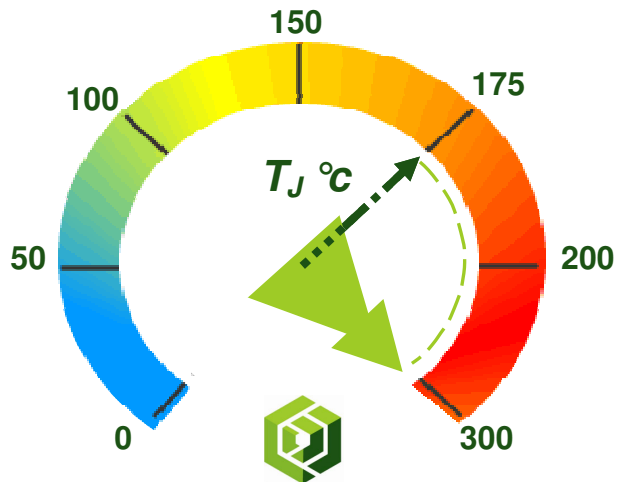
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TEMPERATURE INDEPENDENT SWITCHING BEHAVIOUR



HIGH MAX OPERATING TEMPERATURE UP TO 300 °C*

BENEFITS:

- High Voltage & Current with Zero Reverse Recovery
- Fast Switching Speeds & Lower Switching Losses
- Device Paralleling without Thermal Runaway
- Reduced Passive Components & Thermal Management
- Extreme Temperature Operation Capabilities*

*Note: Performances will vary depending on assembly techniques